

Notice of References Cited	Application/Control No. 10/528,160		Applicant(s)/Patent Under Reexamination HAZEYAMA ET AL.	
	Examiner Earl N. Taylor		Art Unit 2818	Page 1 of 1

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*	B	US-5,394,303	02-1995	Yamaji, Yasuhiro	257/777
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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